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February 22, 2002

To: Commissioner of Patents and Trademarks

Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572

20 McIntosh Drive

Poughkeepsie, N.Y. 12603

TO TOO TOO

Subject:

Serial No. 10/043,603 01/14/02

J. Briar

MOLDED STIFFENER FOR FLEXIBLE

CIRCUIT MOLDING

Grp. Art Unit: 1732

RECEIVED
SEP-4 2002

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on February 27, 2002.

Stephen B. Ackerman, Reg.# 37761

SEP 0 6 2002

Signature/Date Stephen B. ackerma sprioz

ST-98-003B

- U.S. Patent 5,506,756 to Haley, "Tape BGA Package Die-Up/Die Down", describes a ball grid array package containing an integrated circuit die that is directly mounted to either a heat sink or a printed circuit board.
- U.S. Patent 5,241,133 to Mullen, III et al., "Leadless Pad Array Chip Carrier", describes a leadless pad array chip carrier package. A semiconductor device is electrically wire bonded and attached with conductive adhesive to a metallized pattern on a printed circuit board.
- U.S. Patent 5,635,671 to Freyman et al., "Mold Runner Removal from a Substrate-Based Packaged Electronic Device", describes encapsulation of an electronic device using injection molding with a two piece mold using a degating region having a material chosen such that the material in the degating region forms a weak bond with the emcapsulant used.

Sincerely,

Stephen B. Ackerman,

Reg. No. 37761